


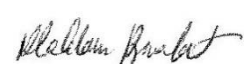

Product and Process Change Notice

PCN No.	PCN03019	PCN Date	12/20/2019	Effective Date	3/19/2020
Title	ChipMOS as additional assembly site for the 1Mb and 256Kb x8 MRAM BGA package				

Type: Major Change			
Everspin is adding ChipMOS as a qualified assembly site for the 1Mb and 256Kb x8 MRAM BGA package.			
Reason For Change			
In order to increase capacity and improve supply flexibility, Everspin is adding ChipMOS as a qualified assembly site for the 1Mb and 256Kb x8 MRAM BGA package.			
Affected Products			
Part Number	Description	Part Number	Description
MR0A08BMA35	Commercial Temp.	MR0A08BMA35R	Commercial Temp., T&R
MR0A08BCMA35	Industrial Temp.	MR0A08BCMA35R	Industrial Temp., T&R
MR0D08BMA45	Commercial Temp.	MR0D08BMA45R	Commercial Temp., T&R
MR0DL08BMA45	Commercial Temp.	MR0DL08BMA45R	Commercial Temp., T&R
MR256A08BMA35	Commercial Temp.	MR256A08BMA35R	Commercial Temp., T&R
MR256A08BCMA35	Industrial Temp.	MR256A08BCMA35R	Industrial Temp., T&R
MR256D08BMA45	Commercial Temp.	MR256D08BMA45R	Commercial Temp., T&R
MR256DL08BMA45	Commercial Temp.	MR256DL08BMA45R	Commercial Temp., T&R
Impact on Form, Fit, Function, Quality or Reliability			
No impact			
Proposed First Ship Date for Change:			
March 20, 2020			
Key Material Differences			
Site	ChipMOS	UDG	
Mold Compound	Sumitomo EME-G760	Nitto GE-100AT	
BLT2 Die Attach	Nitto EM-710 (DAF)	Henkel QMI536NB	
BLT3 Die Attach	Henkel QMI550	Henkel QMI536NB	
Product Identifier			
Assembly site code = H for ChipMOS Taiwan			
Supplier Qual Plan Schedule and Results			
Qualification is complete and all Everspin requirements met; a qualification report is available on request.			
Date Qualification Samples Are Available:			
Samples are generally available now but please request your specific part number to your Everspin Sales contact.			
Acceptance of Change			
Everspin will consider this change accepted unless specific conditions for acceptance are provided in writing within 30 days of receipt of this notice.			

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Contact Information		Sample Information	<input checked="" type="checkbox"/> Samples Available Now
Product Marketing Everspin Technologies (480) 347-1111		Contact Everspin sales: http://www.everspin.com/contact-us-everspin-technologies If using the on-line sample request please refer to this PCN # to receive samples.	
Originator			
<u>Date</u> 12/18/2019	<u>Title</u> Senior Quality Engineer	<u>Name</u> Paul Drobny	
Approval and Release			
<u>Date</u> 12/18/2019	<u>Title</u> Director of Quality	<u>Name</u> Khaldoun Barakat	
<u>Date</u> 12/18/2019	<u>Title</u> VP of Operations	<u>Name</u> Norm Armour	
<u>Date</u> 12/18/2019	<u>Title</u> VP of Sales & Marketing	<u>Name</u> Troy Winslow	